

EUROPEAN PATENT OFFICE

Patent Abstracts of Japan

PUBLICATION NUMBER : 11106506
PUBLICATION DATE : 20-04-99

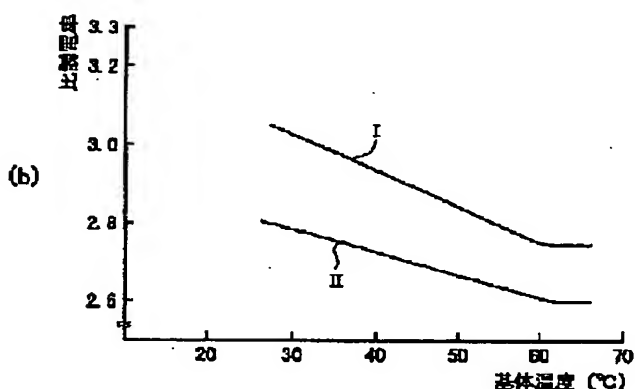
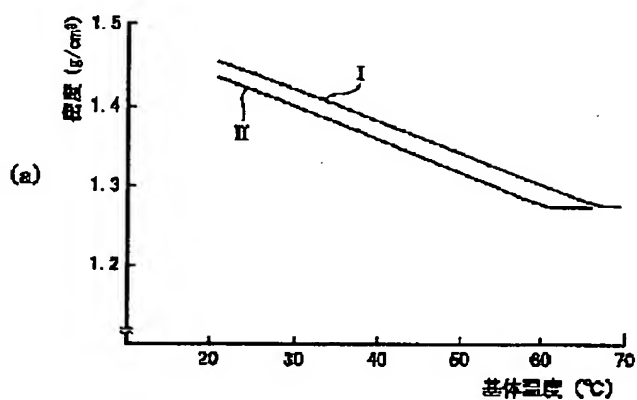
APPLICATION DATE : 03-10-97
APPLICATION NUMBER : 09287740

APPLICANT : ULVAC CORP;

INVENTOR : UKISHIMA YOSHIYUKI;

INT.CL. : C08G 73/10

TITLE : LOWLY PERMITTIVE POLYMER
MEMBRANE, FORMATION THEREOF
AND LAYER INSULATION MEMBRANE



ABSTRACT : PROBLEM TO BE SOLVED: To provide a method for forming simply and easily a lowly permissive polymer membrane which has stable properties and is applicable particularly to interlaminar insulation membranes for semiconductor apparatus.

SOLUTION: In the formation of a polyimide membrane on a substrate by the vapor deposition polymerization, the substrate is heated to and maintained at a temperature of 30°C or above. Among raw monomers for forming the polyimide membrane are, for example, 2,2-bis[4-(4-aminophenoxy) phenyl]hexafluoropropane and 2,2-bis(3,4-phenylcarboxyl)hexafluoropropane dihydrate. The density of the polyimide membrane is reduced to 1.4 g/cm³ or less, with the result that a polyimide membrane having a relative permittivity of 2.6-2.7 can be formed.

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